

Data Sheet

Customer: _____

Product: Thick Film Chip Resistor. High Power Rating ($\geq 1\Omega$) HPF Series _____

Size : 0603/0805/1206/1210/2512 _____

Issued Date: 1-Apr.-2015 _____

Edition: Ver. 1 _____

Record of change

Date	Ver.	Description	Page
1-Apr.-2015	1		
27-Jul-2020	2		2

HITANO ENTERPRISE CORP.

7F-7, No. 3, Wu Chuan 1st Road, New Taipei Industrial Park,

New Taipei City, TAIWAN, R.O.C.

Tel: +886 2 2299 1331 (Rep.)

Fax: +886 2 2298 2466, 2298 2969

Prepared by	Checked by	Approved by	Accepted by (customer)
1-Apr.-2015	1-Apr.-2015	1-Apr.-2015	
<i>Andy Hsu</i>	<i>Hwa Wu</i>	<i>Hwa Wu</i>	

THICK FILM CHIP RESISTORS HIGH POWER

HPF SERIES

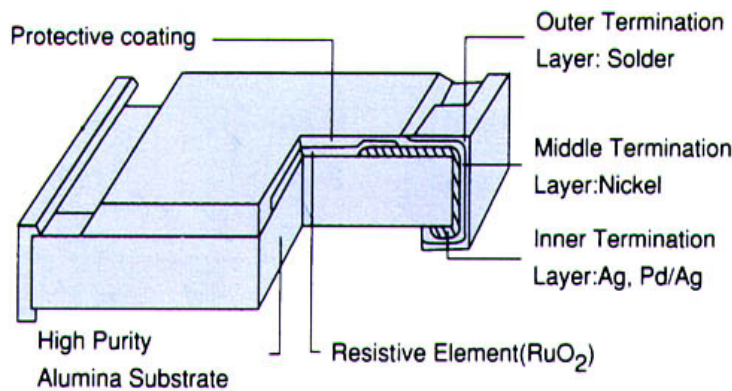
■ Features

- Suitable for lead free soldering.
- Compatible with flow and reflow soldering

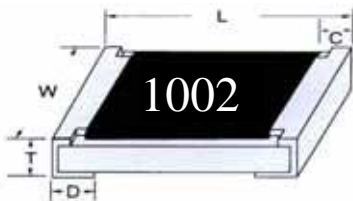
■ Applications

- Consumer Electronics
- SMPS, M/B
- Portable Device
- Measurement instrument
- Electronic equipment

■ Configuration



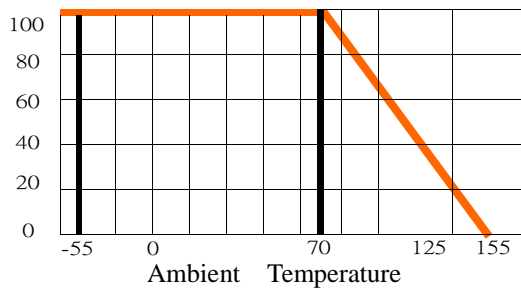
■ Dimensions



Size	L	W	C	D	T
0603	1.60±0.10	0.80±0.10	0.30±0.20	0.30±0.20	0.45±0.15
0805	2.00±0.10	1.25±0.10	0.40±0.20	0.40±0.20	0.50±0.15
1206	3.10±0.10	1.60±0.10	0.50±0.25	0.50±0.25	0.60±0.15
1210	3.10±0.10	2.60±0.10	0.50±0.20	0.50±0.20	0.55±0.10
2010	5.00±0.20	2.50±0.20	0.60±0.25	0.60±0.25	0.55±0.10
2512	6.40±0.20	3.20±0.20	0.60±0.25	0.60±0.25	0.60±0.10

Unit(mm)

■ Power Derating Curve



Maximum dissipation in percentage of rated power as a function of the ambient temperature for 0603,0805,1206,1210,2010,2512

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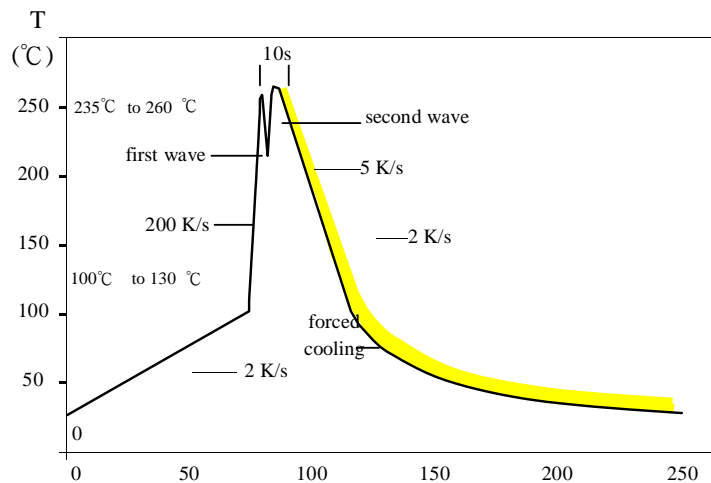
■ Rating

Type	Size	Power Rating at 70°C	Max. RC WV	Max. Overload Voltage	Resistance Tolerance (%)	Temperature Coefficient (TCR; ppm/°C)	Resistance Range (Ω)		Standard Resistance Values
							Min.	Max.	
HPF0603	0603	1/8W	50V	100V	±1% (F)	±100	10Ω	1MΩ	E-96
HPF0805	0805	1/4W	150V	300V					
HPF1206	1206	1/2W	200V	400V					
HPF1210	1210	1/2W	200V	400V	±5% (J)	±200	0Ω , 1Ω	10MΩ	E-24
HPF2010	2010	1W	200V	400V					
HPF2512	2512	2W	300V	600V					

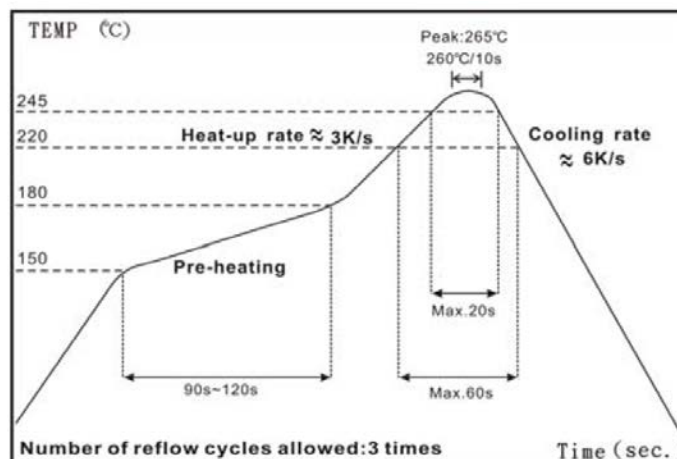
Note : (1) RCWV = $(P \times R)^{1/2}$ or Max. RCWV listed above, whichever is lower

RCWV: Working Voltage(V). P: Rated Power (W), R: Resistance Value(Ω)

■ Soldering Temperature Curve



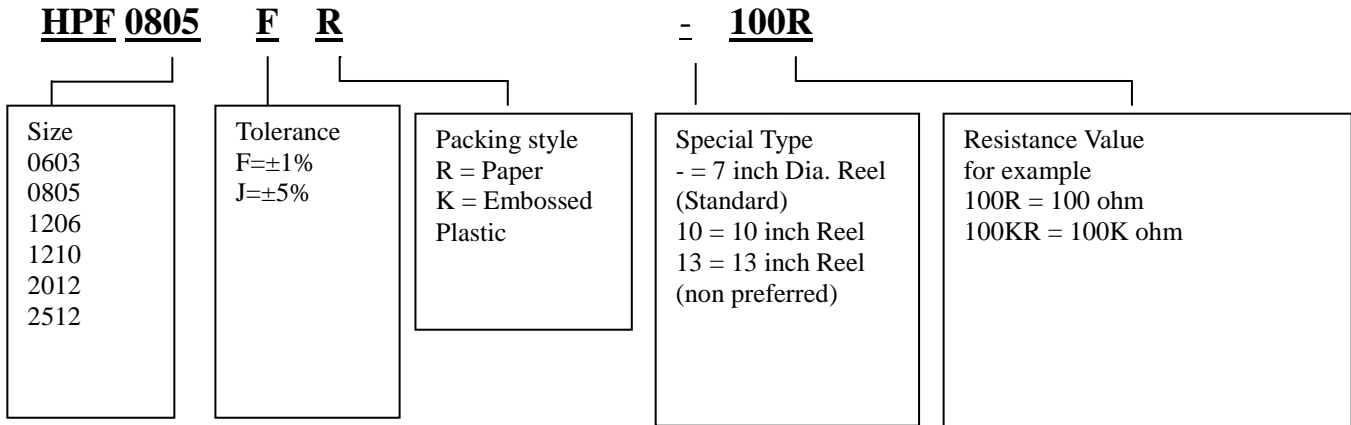
Process limits (dotted line). **WAVE soldering.**



IR Reflow Soldering

THICK FILM CHIP RESISTORS HPF SERIES HIGH POWER

■ Part Numbering



GENERAL SPECIFICATION

■ Resistance Marking



3 digit marking for E-24 ±5% 0603 0805 1206 1210 2010 2512
example : **301** $30 \times 10^1 = 300 \Omega$



4 digit marking for E-96 ±1% 0805 1206 1210 2010 2512
example : **1542** $154 \times 10^2 = 15K4 \Omega$



3 digit marking for E-24 ±1% 0603
example : **222** $22 \times 10^2 = 2K2 \Omega$

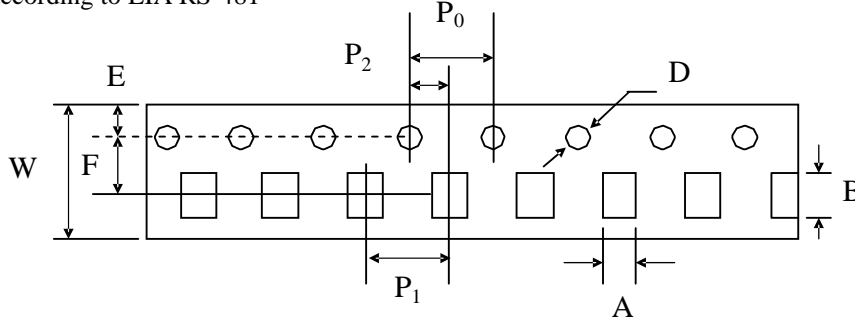


3 digit marking for E-96 ±1% 0603
example : **01C** $10K \Omega$

THICK FILM CHIP RESISTORS HPF SERIES HIGH POWER

■ Tape And Reel Package

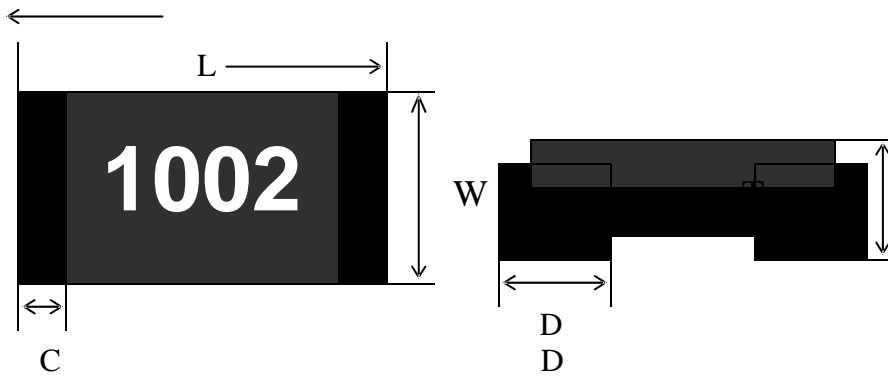
• Taping specs are according to EIA RS-481



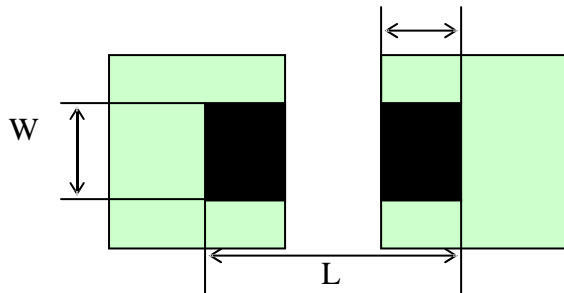
Accumulated dimensional tolerance $40\pm 0.2\text{mm}$

Size	A	B	W	F	E	P1	P2	P0	D
0603	1.10 ± 0.20	1.90 ± 0.20	8.00 ± 0.30	3.50 ± 0.05	1.75 ± 0.10	4.00 ± 0.10	2.00 ± 0.05	4.00 ± 0.10	$1.50+0.10/-0$
0805	1.65 ± 0.20	2.40 ± 0.20	8.00 ± 0.30	3.50 ± 0.05	1.75 ± 0.10	4.00 ± 0.10	2.00 ± 0.05	4.00 ± 0.10	$1.50+0.10/-0$
1206	2.00 ± 0.20	3.60 ± 0.20	8.00 ± 0.30	3.50 ± 0.05	1.75 ± 0.10	4.00 ± 0.10	2.00 ± 0.05	4.00 ± 0.10	$1.50+0.10/-0$
1210	3.00 ± 0.20	3.60 ± 0.20	8.00 ± 0.30	3.50 ± 0.05	1.75 ± 0.10	4.00 ± 0.10	2.00 ± 0.05	4.00 ± 0.10	$1.50+0.10/-0$
2010	2.80 ± 0.20	5.50 ± 0.20	12.00 ± 0.30	5.50 ± 0.05	1.75 ± 0.10	4.00 ± 0.10	2.00 ± 0.05	4.00 ± 0.10	$1.50+0.10/-0$
2512	3.50 ± 0.20	6.70 ± 0.20	12.00 ± 0.30	5.50 ± 0.05	1.75 ± 0.10	4.00 ± 0.10	2.00 ± 0.05	4.00 ± 0.10	$1.50+0.10/-0$

(unit: mm)



* 2W loading with total solder-pad and trace size of 300mm^2

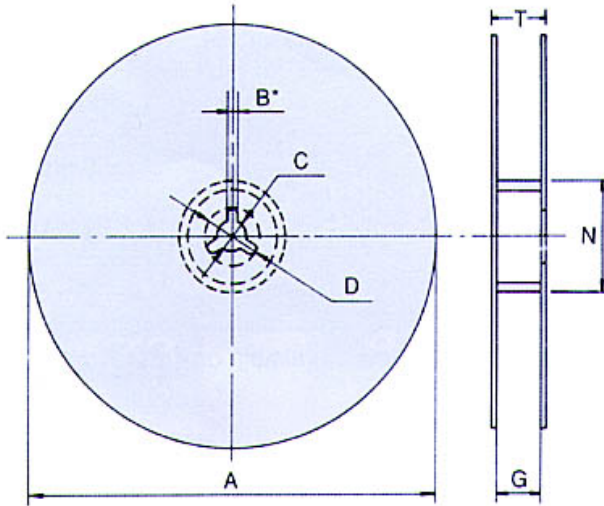


Type	W	D	L
HPF2512	3.7mm	2.45mm	7.6mm

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HPF SERIES

■ **Reel Package**



Size	Packaging Q'ty	A	N	C	D	B	G	T
0603 0805 1206 1210	5Kpcs / Reel	178.0±2.0	60.0±0.5	13.0±0.5	20min	2.0±0.5	10.0±1.5	14.9 max.
	10Kpcs / Reel	254.0±2.0	100.0±1.0	13.5±0.5	20min	2.0±0.5	10.0±1.5	14.9 max.
	20Kpcs / Reel	330.0±2.0	100.0±1.0	13.5±0.5	20min	2.0±0.5	10.0±1.5	14.9 max.
2010 2512	4Kpcs / Reel	178.0±2.0	60.0±0.5	13.0±0.5	20min	2.0±0.5	13.8±1.5	16.7 max.
	8Kpcs / Reel	254.0±2.0	100.0±1.0	13.5±0.5	20min	2.0±0.5	13.8±1.5	16.7 max.
	16Kpcs / Reel	330.0±2.0	100.0±1.0	13.5±0.5	20min	2.0±0.5	13.8±1.5	20.0 max.

(unit: mm)

THICK FILM CHIP RESISTORS HPF SERIES

HIGH POWER

■ HPF > 1Ω Specification And Test Methods

ITEM	SPECIFICATION	TEST METHOD
DC Resistance	J: ±5% , F: ±1%	IEC 60115-1 / JIS C 5201-1 , Clause 4.5 Measure the resistance value.
Short time Overload	J: $\Delta R \leq \pm (2\% + 0.5m\Omega)$ F: $\Delta R \leq \pm (1\% + 0.5m\Omega)$	IEC 60115-1 / JIS C 5201-1 , Clause 4.13 2.5×Rated voltage or Max. Overload Voltage for 5 sec. measure resistance after 30 minutes
Solderability	Over 95% of termination must be covered with solder	IEC 60115-1 / JIS C 5201-1 , Clause 4.17 After immersing flux, dip in the 235±2°C molten solder bath for 2±0.5 sec.
Resistance to Solder Heat	J: $\Delta R \leq \pm (1\% + 0.5m\Omega)$ F: $\Delta R \leq \pm (0.5\% + 0.5m\Omega)$ No mechanical damage	IEC 60115-1 / JIS C 5201-1 , Clause 4.18 With 260±5°C for 10±1 sec.
Temperature Coefficient (TCR)	As Spec.	IEC 60115-1 / JIS C 5201-1 , Clause 4.8 -55°C ~ +125°C, 25°C is the reference temperature
Load Life Humidity	J: $\Delta R \leq \pm (3\% + 0.5m\Omega)$ F: $\Delta R \leq \pm (1\% + 0.5m\Omega)$	IEC 60115-1 / JIS C 5201-1 , Clause 4.24 Maintain the temperature of the resistor at 40±2°C and 90 ~ 95% R.H. with the rated voltage applied. Cycle ON for 1.5 hours and OFF for 0.5 hour for 1000+48/-0 hours. After 1~4 hour, measure
Load Life	J: $\Delta R \leq \pm (3\% + 0.5m\Omega)$ F: $\Delta R \leq \pm (1\% + 0.5m\Omega)$	IEC 60115-1 / JIS C 5201-1 , Clause 4.25 Permanent resistance change after 1000+48/-0 hours (1.5 hours ON , 0.5 hour OFF) at RCWV or Max. Keep the resistor at 70±2°C ambient
Temperature Cycle	J: $\Delta R \leq \pm (1\% + 1m\Omega)$ F: $\Delta R \leq \pm (0.5\% + 1m\Omega)$ No mechanical damage	IEC 60115-1 / JIS C 5201-1 , Clause 4.19 Repeat 5 cycles as follows -55°C (30 min.) + 25°C (2~3 min.) +125°C (30 min.) + 25°C (2~3 min.) for 0201 55°C (30 min.) + 25°C (2~3 min.) +155°C (30 min.) + 25°C (2~3 min.) for others
Insulation Resistance	Between termination and coating must be over 1000MΩ	IEC 60115-1 / JIS C 5201-1 , Clause 4.6 Test voltage: 100±15V
Bending Strength	J: $\Delta R \leq \pm (1\% + 1m\Omega)$ F: $\Delta R \leq \pm (0.5\% + 1m\Omega)$ No mechanical damage	IEC 60115-1 / JIS C 5201-1 , Clause 4.33 Resistance change after bended on the 90mm PCB Bend: 3mm for 0603、0805 2mm for 1206、1210、2010、2512